

Abstract

The invention relates to a high oxygen barrier, multilayer flexible packaging structure having a vacuum metallized, biaxially oriented polypropylene (met-BOPP) or metallized polyester (met-PET) film substrate; a high barrier EVOH layer coextruded or laminated directly on the metal-containing layer; and optionally an adjacent layer of anhydride modified polyolefin such as blend of LDPE, or MDPE, or PP and maleic anhydride modified adhesive resin on the EVOH layer.